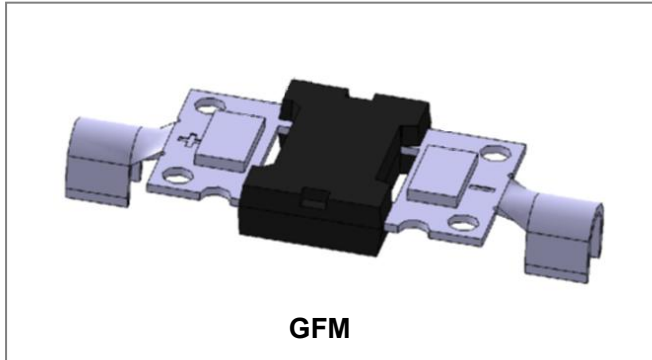


GF5045PC SCHOTTKY RECTIFIER



Features

- Schottky Barrier high diode
- Low thermal resistance
- Lower forward voltage drop, low power loss
- Isolate Package design, ideal for heat dispersion
- High forward current capability
- Excellent anti-humidity
- Low profile package
- High forward surge capability
- Terminals: Tin plated
- All SMC parts are traceable to the wafer lot
- Additional electrical and life testing can be performed upon request

Mechanical Data

- Case: GFM
- Terminals: Copper
- High temperature soldering guaranteed
- Heated-tool welding 260°C, 10seconds
- Marking Code: GF5045PC

Maximum Ratings (limiting values, at 25 °C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	-	45	V
Average Rectified Forward Current	$I_F (AV)$	$T_C = 105^\circ\text{C}$, In DC	50	A
Peak One Cycle Non-Repetitive Surge Current	I_{FSM}	8.3 ms, half Sine pulse	450	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	V_{F1}	@ 50A, Pulse, $T_J = 25^\circ\text{C}$	0.49	0.60	V
Reverse Current*	I_{R1}	@ $V_R = \text{rated } V_R$, $T_J = 25^\circ\text{C}$	0.20	1.0	mA
	I_{R2}	@ $V_R = \text{rated } V_R$, $T_J = 125^\circ\text{C}$	115	200	mA
Junction Capacitance	C_T	@ $V_R = 5\text{V}$, $T_C = 25^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	4546	-	pF

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	IN DC Forward Mode, without reverse bias, $t \leq 1$ h	-55 to +200	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	-	1.5	$^{\circ}\text{C/W}$

Ratings and Characteristics Curve

Figure 1 Typical Forward Characteristics

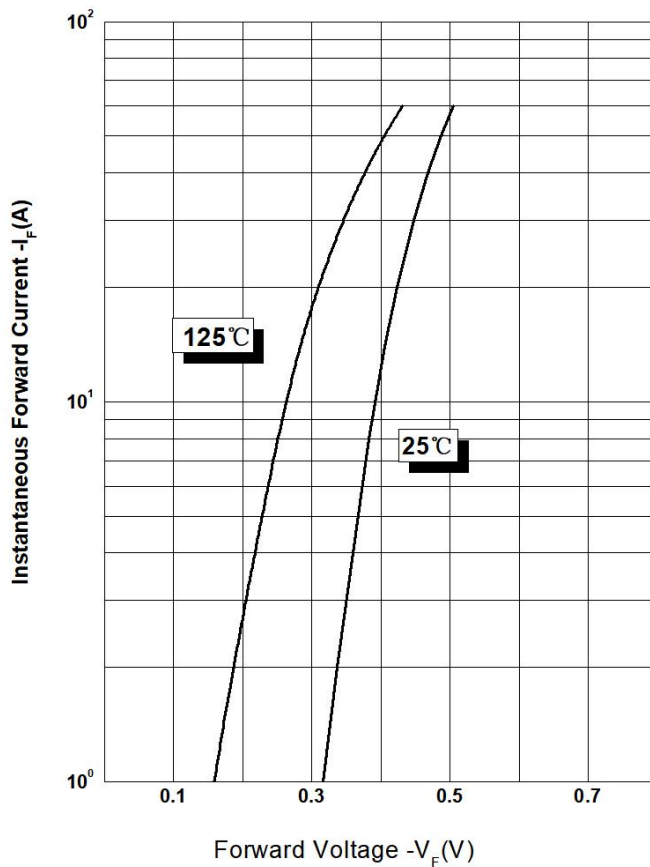


Figure 2 Typical Reverse Characteristics

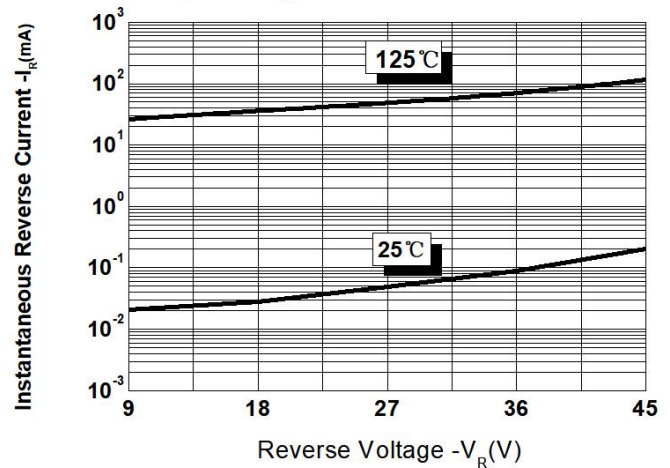
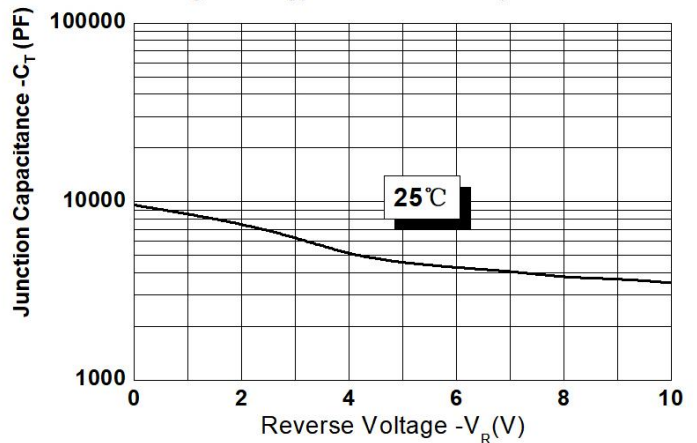


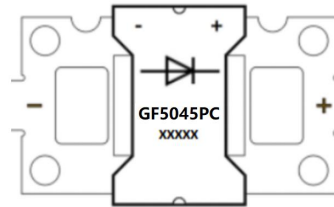
Figure 3 Typical Junction Capacitance



Ordering Information

Device	Package	Shipping
GF5045PC	GFM	30pcs / Tube

Marking Diagram



Where XXXXX is YYWWL

GF5045PC = Marking Code
YY = Year
WW = Week
L = Lot Number

Order P/N	Terminals	Additional
GF5045PC-S1	Tin Plated	None
GF5045PC-S2	Tin Plated	Solder Paste
GF5045PC-S3	Tin Plated	Solder Block
GF5045PC-N1	Nickel Plated	None
GF5045PC-N2	Nickel Plated	Solder Paste
GF5045PC-N3	Nickel Plated	Solder Block

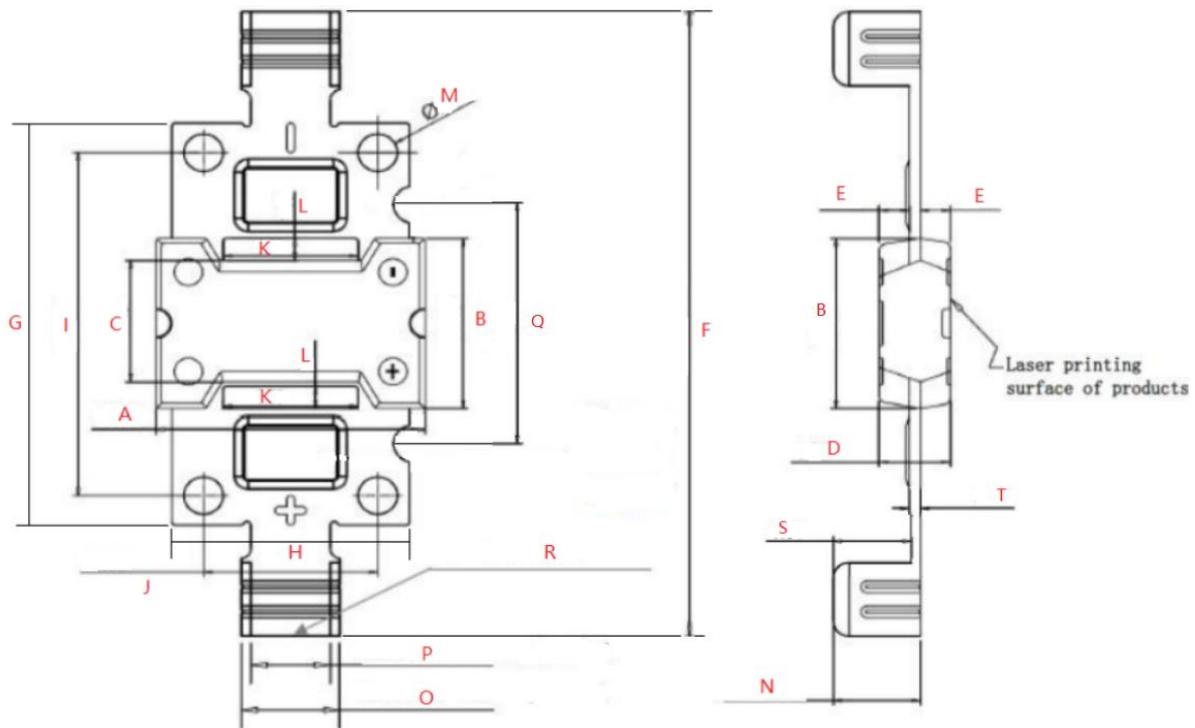


Solder Paste



Solder Block

Mechanical Dimensions GFM (Millimeters)



Symbol	Dimensions in millimeters		
	Min.	Typical	Max
A	16.90	17.00	17.10
B	11.38	11.48	11.58
C	8.15	8.20	8.25
D	4.40	4.50	4.60
E	1.85	1.90	1.95
F	41.90	42.00	42.10
G	26.90	27.00	27.10
H	14.90	15.00	15.60
I	22.90	23.00	23.10
J	10.90	11.00	11.10
K	-	8.50	-
L	-	1.50	-
M	-	∅ 2.50	2.55
N	5.35	5.50	5.65
O	6.20	6.30	6.40
P	4.90	5.00	5.10
Q	15.95	16.00	16.05
R	2.80	2.90	3.00
S	4.75	4.80	4.85
T	0.67	0.70	0.73

Dimension H includes Burrs/cutting residuals.

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- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
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